Issue Date: 2009-01-12 Page 1 of 1 Report Reference # E203413-A46-CB-4

Correction 1 2009-01-13

COVER PAGE FOR TEST REPORT

Test Item Description: Personal Computer

Model/Type Reference: MS-6289, MS-6410xxxxxx, Hetis 945xxxxxx, Hetis 915xxxxxx, MS-6415xxxxxx,

Hetis 800xxxxxx, AE510, iShared mini, MS-6439XX, Hetis 900, MS-6441XX, Hetis 965XX, MS-6470XX, Hetis G31XX, MS-6618XXXX and Hetis G41XXXX

(where x and X = A-Z, 0-9 or blank, and no impact any critical safety

components and constructions)

Rating(s): 100-127 Vac / 200-240 Vac, 6 A / 3 A, 47-63 Hz

Standards: IEC 60950-1:2001, First Edition and/or EN 60950-1:2001 + A11:2004

Applicant Name and MICRO-STAR INTERNATIONAL CO LTD

Address:

69 LI-DE ST CHUNG HO

TAIPEI HSIEN 235 TAIWAN

Factory Location(s): 1.

MSI ELECTRONICS (KUNSHAN) CO LTD

88 E QUANJIN RD, KUNSHAN JIANGSU 215300, CHINA

2.

MSI COMPUTER (SHENZHEN) CO LTD

LONGMA INFORMATION TECHNOLOGY IND PARK, TANGTOU VILLAGE SHIYAN TOWN, BAO'AN DISTRICT, SHENZHEN GUANGDONG, CHINA

3.

MICRO-STAR INTERNATIONAL CO LTD

69 LI-DE ST, CHUNG HO TAIPEI HSIEN 235, TAIWAN

4.

NETWORK ENGINES INC

25 DAN RD, CANTON, MA 02021, UNITED STATES

This Report includes the following parts, in addition to this cover page:

1. Specific Technical Criteria

2. Critical Components

3. Enclosures

a. Photographs

b. Diagrams

The original report was modified on 2009-01-13 to include the following changes/additions:

- This test report was deemed to correct, due to:

Correct the model names from Heits G31XX, Heits G41XXXX to Hetis G31XX, Hetis G41XXXX.

All applicable tests according to the above standard(s) have been carried out.

Test results are valid only for the tested equipment.

This Test Report can be reproduced only in whole.

Amendments and corrections can be reproduced only with the original CB Test Report.

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Correction 1 2009-01-13



Test Report issued under the responsibility of:



UL International Demko A/S

TEST REPORT IEC 60950-1,First Edition Information technology equipment-Safety Part 1:General Requirements

Report Reference No E203413-A46-CB-4

Date of issue 2009-01-12

Total number of pages: 27

CB Testing Laboratory Underwriters Laboratories Taiwan Co., Ltd.

Address 260 Da-Yeh Road, 112 Peitou Taipei City, Chinese Taipei

Applicant's name MICRO-STAR INTERNATIONAL CO LTD

69 LI-DE ST Address: CHUNG HO

TAIPEI HSIEN 235 TAIWAN

Test specification:

Standard IEC 60950-1:2001, First Edition

Test procedure CB Scheme

Non-standard test method: N/A

 Test Report Form No.
 IEC60950_1B

 Test Report Form originator
 SGS Fimko Ltd

 Master TRF
 dated 2003-03

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Test item description Personal Computer

Trade Mark: MSI

Model/Type reference MS-6289, MS-6410xxxxxx, Hetis 945xxxxxx, Hetis 915xxxxxx, MS-

6415xxxxxx, Hetis 800xxxxxx, AE510, iShared mini, MS-6439XX, Hetis 900, MS-6441XX, Hetis 965XX, MS-6470XX, Hetis G31XX, MS-6618XXXX and Hetis G41XXXX (where x and X = A-Z, 0-9 or

blank, and no impact any critical safety components and

constructions)

Manufacturer SAME AS APPLICANT

Rating: 100-127 Vac / 200-240 Vac, 6 A / 3 A, 47-63 Hz

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Testing	g procedure and testing location:		
[x]	CB Testing Laboratory		
	Testing location / address::	Underwriters Laboratories Taiw Road, 112 Peitou Taipei City, C	
[]	Associated CB Test Laboratory		
	Testing location / address::		
	Tested by (name + signature):	Reon Tsai	Remose
	Approved by (+ signature):	Frank Liu	Readse -
[]	Testing Procedure: TMP		
	Tested by (name + signature):		
	Approved by (+ signature)::	•	
	Testing location / address::	•	
[]	Testing Procedure: WMT		
	Tested by (name + signature):		
	Witnessed by (+ signature):		
	Approved by (+ signature)::		
	Testing location / address::		
[]	Testing Procedure: SMT		
	Tested by (name + signature):		
	Approved by (+ signature)::	•	
	Supervised by (+ signature)::		
	Testing location / address:		
[]	Testing Procedure: RMT		
	Tested by (name + signature):		
	Approved by (+ signature)::		
	Supervised by (+ signature):		
	Testing location / address:		

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Correction 1 2009-01-13

Summary of Testing:

No tests were conducted

Summary of Compliance with National Differences:

AR, AT, AU, BE, CA, CH, CN, CZ, DE, DK, EU, FI, FR, GB, GR, HU, IL, IN, IT, JP, KE, KR, MY, NL, NO, NZ, PL, SE, SG, SI, SK, US

Copy of Marking Plate - Refer to Enclosure titled Marking Plate for copy.

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Correction 1 2009-01-13

Test item particulars:

Tested for IT power systems No

motherboard/ MS-7231) and 8 (for motherboard/ MS-7259 and MS-7331), 8.2 (for motherboard/ MS-7334), 8.24 (for motherboard/ MS-7407), and 8.24 (for

8.24 (10f motherboard/ MS-7407), and 8.24 (10

motherboard/ MS-7430)

Protection against ingress of water IP X0

Possible test case verdicts:

test case does not apply to the test object
 test object does meet the requirement
 P(Pass)
 test object does not meet the requirement

Testing:

General remarks:

The test results presented in this report relate only to the object tested.

This report shall not be reproduced, except in full, without the written approval of the Issuing testing laboratory.

"(see Enclosure #)" refers to additional information appended to the report.

"(see appended table)" refers to a table appended to the report.

Throughout this report a point is used as the decimal separator.

Refer to the Cover Page For Test Report for a list of all Factory Locations.

GENERAL PRODUCT INFORMATION:

Report Summary

The original report was modified on 2009-01-13 to include the following changes/additions:

- This test report was deemed to correct, due to:

Correct the model names from Heits G31XX, Heits G41XXXX to Hetis G31XX, Hetis G41XXXX.

Product Description

Consist of power supply, RTC Battery, DC fans, HDD, CD-ROM/ DVD-ROM and electronic components mounted on PWB, and housed in metallic enclosure, secured together by screws.

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Correction 1 2009-01-13

Model Differences

- Models MS-6410xxxxxx, MS-6415xxxxxx, Hetis 800xxxxxx, Hetis 945xxxxxx and Hetis 915XXXXX, where X and x = A-Z, 0-9 or blank, are identical to MS-6289 except for model designation and Mainboard type.

- Model AE510 is identical to Model Hetis 915XXXXX except for model designation.
- Model iShared mini is identical to Model Hetis 915XXXXX except for model designation.
- Models MS-6439XX and Hetis 900 are identical to Model MS-6410 except for model designation.
- Models MS-6441XX and Hetis 965XX are similar to Model MS-6410 except for model designation and Mainboard type.
- Model MS-6441XX is identical to Model Hetis 965XX except for model designation.
- Models MS-6470XX and Hetis G31XX are identical to Model Hetis 965XX except for model designation and Mainboard type.
- Models MS-6618XXXX and Hetis G41XXXX are similar to Model MS-6470XX except for model designation and Mainboard type.
- Model Hetis G41XXXX is similar to Model MS-6618XXXX except for model designation.

Additional Information

- Models MS-6415xxxxxx and Hetis 800xxxxxx are for Mainboard MS-7259.
- Models MS-6410xxxxxx and Hetis 945xxxxxx are for Mainboard MS-7231.
- Models MS-6289, Hetis 915XXXXX, AE510 and iShared mini are for Mainboard MS-7137.
- Models MS-6439XX and Hetis 900 are for Mainboard MS-7331.
- Models MS6441XX and Hetis 965XX are for Mainboard MS-7334.
- Models MS-6470XX and Hetis G31XX are for Mainboard MS-7407.

Models MS-6618XXXX and Hetis G41XXXX are for Mainboard MS-

For project 07CA46287:

- Revised main board connecter circuit of MSI., P/N MS-7334.

For project 07CA50270:

- Revised main board connecter circuit of MSI., P/N MS-7407.

For project 07CA62891:

-Alternate metal enclosure.

- For report issue 4, re-issue, included below revision:

01, add new models MS-6618XXXX and Hetis G41XXXX;

02, alternate mainboard type MS- 7430 for models MS-6618XXXX and Hetis G41XXXX only.

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Correction 1 2009-01-13

For CB, 08CA59344:

This report is re-issued from E203413-A46-CB-3 with Amendment 3 issued 2007-12-26, with CB Certificate No. (DK-11718-A4, DK-11719-A3, DK-11720-A3), issued 2008-01-02 due to modify below items:

- (01). Add new models MS-6618XXXX and Hetis G41XXXX (where x and X = A-Z, 0-9 or blank, and no impact any critical safety components and constructions).
- (02). Alternate mainboard type MS- 7430 for models MS-6618XXXX and Hetis G41XXXX.
- (03). Delete the trademark NETWORK ENGINES, INC and PACKETEER, INC.
- (04). Revise the address of factory NETWORK ENGINES INC from 25 DAN RD, CANTON, MA 02021, USA to 25 DAN RD, CANTON, MA 02021, United States.
- Only the following tests were deemed necessary:
- 1.6.2- INPUT TEST: SINGLE-PHASE Test.
- 2.5- Limited Power Source Measurements Test.
- 4.1-Stability Test
- 4.3.8- Lithium Battery Reverse Current Measurement Test.
- 4.5.1, 1.4.12, 1.4.13- Heating Test.
- 5.3.1, 5.3.8.2- Abnormal Operation Test.
- 5.3.6- Overload of operator Accessible Connector Test.

Technical Considerations

The product was submitted and tested for use at the maximum ambient temperature (Tma) permitted by the manufacturer's specification of: 40°C

The means of connection to the mains supply is: Detachable power cord, Pluggable A

The product is intended for use on the following power systems: IT, TN

The equipment disconnect device is considered to be: Appliance inlet

The class of laser product is: Class 1 (I), applied on R/C CD-Rom and/or DVD-Rom.,

The product was investigated to the following additional standards: EN 60950-1:2001 + A11:2004 (which includes all European national differences, including those specified in this test report)., U.S. Code of Federal Regulations, 21 CFR 1040 and IEC 60825-1..

The following circuit locations (with circuit/schematic designation) were investigated as a limited power source (LPS): USB ports, PS/2 ports, IEEE1394 ports.

The power supply in this equipment was: Investigated to an earlier edition/amendment of IEC 60950. As part of the investigation of this product, the power supply and its test report were reviewed and found to comply with IEC 60950-1.

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IEC 60950-1				
Clause	Requirement + Test	Result - Remark	Verdict	

1.5.1 T	ABLE: list of critic	al components				Pass
object/part No.	. manufacturer/ trademark	type/model	technical data	standard	mark	c(s) of ormity ¹)
2. Power supp cord (Optional)			Detachable, Type SVT or SPT-2, 125/250 V min., 18 AWG min., 4.5 m long max., one end with, grounding type, NEMA 5- 15P/ NEMA 6- 15P. Other end with appliance coupler.	UL62, UL498, or UL817	UL, -	-
3. Metal Enclosure			Consists of two parts, secured together by physical fit and screw, Overall 330 by 320 by 94 mm, 0.8 mm thick minimum for both parts, see enclosure 4-01.		,	
3a. Metal Enclosure (Alternate)			Consists of two parts, secured together by physical fit and screw, Overall 330 by 320 by 94 mm, 0.8 mm thick minimum for both parts, see enclosure 4-09.		,	
4. Plastic Pane	el		HB minimum, overall 320 by 94 by 44 mm, 2.5 mm thickness minimum, secured to enclosure by screws.	UL94	UL, -	-
5A. Connector and Receptacl		Metal/Plastic	Copper alloy pins housed in	UL94	UL, -	-

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IEC 60950-1				
Clause	Requirement + Test	Result - Remark	Verdict	

1	1	т	1	T	T
(Secondary			bodies of plastic		
ELV/SELV			rated V-2 min.		
circuits)					
5B. Connectors				UL498, UL1977.	UL,
and Receptacles					,
(Secondary					
ELV/SELV					
circuits)					
5C. Connectors,			Type RJ-45	UL1863	UL,
(for network)					
6. Built-in Power	Delta Electronics	DPS-250AB-7	I/P: 100-127	UL60950,	UL, TUV
Supply	Inc.	XX	Vac/7 A, 200-	IEC60950-1:	Rheinland,
'''			240 Vac/4 A, 47-	2001, EN60950-	Certificate No.
			63 Hz, O/P: DC	1: 2001.	JPTUV-010215,
			+3.3 V/16.0 A,	200	Test Report
			+5 V/16.0 A, +12		Reference No.
					11003719 001.
			V/16.0 A, +5		11003719001.
			Vsb/2 A, -12		
			V/0.8 A. Class I.		
06a. Built-in	FSP Group Inc.	FSP250-50MSP	I/P: 100-	UL60950,	UL, TUV
Power Supply			120/220-240	IEC60950-1:	(Certificate No.
(Alternate)			Vac, 60/50 Hz,	2001, EN60950-	JPTUV-014499,
(For model MS-			6/3 A. O/P: DC	1: 2001.	Test Report
6415xxxxxxx			+3.3 V/16.0 A,		Reference No.
Hetis 800xxxxxx,			+5 V/16.0 A, +12		11006604 001)
MS-6410xxxxxx,			V/16.0 A, +5		1100000+001)
Hetis 945xxxxxx			Vsb/2 A, -12		
with main board			V/0.8 A. +3.3 V		
MS-7231, MS-			& +5 V & +12 V		
7259, MS-			= 234 W		
6439XX and			maximum, +3.3		
Hetis 900)			V & +5 V = 110		
(Also for Model			W maximum,		
MS-6441XX,			Total output		
Hetis 965XX with			power = 250 W		
main board MS-			maximum. Class		
7334)			I.		
(Also for Model			' '		
MS-6470XX,					
Hetis G31XX					
with main board					
MS-7407)					
(Also for Models					
MS-6618XXXX					
and Hetis					
G41XXXX with					
main board MS-					
7430)					
1+30)		l	1		l

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IEC 60950-1				
Clause	Requirement + Test	Result - Remark	Verdict	

7. Plastic Stand Base	Various	Various	Minimum HB, 60 degree C, 0.175Kg, dimension see diagram 4-10 for detail.	UL498, UL1977.	UL,
8. System Fan	Sunonwealth Electric Machine Industry Co., Ltd.	KDE1206PHV2	One provided, rated 12 Vdc, 0.09 A, 18 CFM	UL507, EN60950-1: 2001	UL, CAS, TUV
8a. System Fan (Alternate)	Delta Electronics Inc.	AFB0612MC	12 Vdc, 0.17 A maximum. 18.15CFM.	UL507	UL,
8-1. Metal mesh for system fan			Metal, secured to enclosure by screw, dimension see diagram 4-13 for detail.		,
9A. Hard Disk (Optional)	Seagate Technology	ST3XXYY-XX	Rated 5 Vdc, 1.5 A maximum; 12Vdc, 1.5A maximum	UL60950-1, EN60950	UL, TUV
9B. Hard Disk (Optional)	Hitachi Global Storage Technology	HDS7225nnVLA Tnn (n:0-9)	Rated 5 Vdc, 1.5 A maximum; 12 Vdc, 2.0 A maximum	UL60950-1, EN60950	UL, TUV
10. Card Reader (Optional)			Connected to connector JFP1 (USB) on mainboard.		,
11A. DVD-ROM Drive (Optional)	Micro-Star International Co., Ltd.	MS-8448M	Rated 5 Vdc/ 12 Vdc, 1.6 A max., Laser Class 1	UL60950-1	UL,
11B. DVD-ROM (Optional)	Pioneer Corporation	DVR-107DB	Rated 5 Vdc, 1.1 A; 12 Vdc, 0.8 A, Laser Class 1	UL60950-1	UL,
12. Insulating tubing/Sleeving			FEP, PTFE, PVC, TFE, neoprene, polyimide or marked VW-1; 105 degree C, 300 V, provided with F1.	UL224	UL,
13. Wiring, internal secondary ELV/SELV			FEP, PTFE, PVC, TFE, neoprene, polyimide or	UL758	UL, UL

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IEC 60950-1				
Clause	Requirement + Test	Result - Remark	Verdict	

		T	1	T	T
circuits			marked VW-1; min 30 V, 80 degree C.		
14. Interconnecting Cable (Optional)			60 degree C min., 60 V min., 3.05 m long max., jacketed except for USB, IEEE 1394 and PS/2 cable, VW- 1 or FT-1	UL758	UL,
15. Internal Plastic Part Materials			V-2 min.	UL94	UL,
16. Speaker (Optional)			8 ohm, 1 W		,
Motherboard, MSI, type MS- 7137					,
01. PWB			V-0 or better, min. 105 degree C	UL796	UL,
02a. CPU Fan	Delta Electronics Inc.	AFB0712HHB- 5B25	One provided, rated 12 Vdc, 0.45 A, 35.31 CFM	UL507, EN60950-1: 2001	UL, CAS, VDE
02b. CPU Fan (alternate)	Delta Electronics Inc.	AFB0812HD	One provided, rated 12 Vdc, 0.27 A, 43.941 CFM.	UL507, EN60950-1: 2001	UL, CAS, VDE
03a. RTC Lithium Battery	Sony Fukushima Corp.	CR2032	3.0 Vdc, 210 mA Max. Abnormal Charging Current 10 mA.	UL 1642	UL,
03b. RTC Lithium Battery (Alternate)	Toshiba Battery Co., Ltd.	CR2032	3.0 Vdc, 210 mA Max. Abnormal Charging Current 10 mA.	UL 1642	UL,
03c. RTC Lithium Battery (Alternate)	Mitsubishi Electric Corp.	CR2032	3.0 Vdc, 210 mA Max. Abnormal Charging Current 10 mA.	UL 1642	UL,
03d. RTC Lithium Battery (Alternate)	Vic-Dawn (KTS) Enterprise Co., Ltd.	CR2032	3.0 Vdc, 220 mA Max. Abnormal Charging Current 10 mA.		UL,
03e. RTC Lithium Battery	Matsushita Electric Industrial	CR2032	3.2 Vdc, 220 mA Max. Abnormal	UL 1642	UL,

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IEC 60950-1				
Clause	Requirement + Test	Result - Remark	Verdict	

(Alternate)	Co Ltd (Panasonic)		Charging Current 10 mA.		
04. Diode (D5)			Min. 30 V, 600 mA.		,
05a-01. Polyswitch (FS1, FS2)	Polytronics Technology Corp	SMD1812P260T S	6 Vdc, 2.6 A, provided for PS2 and USB connectors.	UL1434	UL,
05a-02. Polyswitch (FS1, FS2) (Alternate)	Tyco Electronics Corp. Raychem Circuit Protection Div	miniSMDM260	6 Vdc, 2.6 A, provided for PS2 and USB connectors.	UL1434	UL,
05a-03. Polyswitch (FS1, FS2) (Alternate)	Tyco Electronics Corp. Raychem Circuit Protection Div	miniSMDC260	6 Vdc, 2.6 A, provided for PS2 and USB connectors.	UL1434	UL,
05b. Polyswitch (FS4)	Tyco Electronics Corp Raychem Circuit Protection Div	miniSMDM150/2 4	PTC, 24 Vdc, 1.5 A, provided for IEEE 1394 connectors.	UL1434, EN60730-1	UL,
06. CPU Heatsink			Consist of Aluminum part and copper part. Overall 95 by 90 by 46 mm, copper part diameter 44 mm, thickness 0.5mm on bottom. Total 33 fins provided, the fin's thickness 0.65 mm, gap between fins 1.9 mm. See enclosure 3-06 & 3-07 for reference.		,
07. Heatsink (above 915 chipset)			Aluminum, overall 42.5 mm by 42.5 mm by 20.8 mm, see Enclosure 4-03 for details.		,
08. Heatsink (above ICH6 chipset)			Aluminum, overall 37.5 mm by 37.5 mm by 6 mm, see		,

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IEC 60950-1				
Clause	Requirement + Test	Result - Remark	Verdict	

	1	T	T=	T	
			Enclosure 4-04		
			for detail.		
09. Heatsink			Aluminum,		,
(HS1, HS2, HS3)			overall 55 mm by		
			24.7 mm by 18		
			mm, see		
			Enclosure 4-05		
			for detail.		
Motherboard,					,
MSI, type MS-					,
7231					
01. Printed			V-1 or better,	UL796	UL,
Wiring Board			Minimum 105	02700	J 2,
Willing Doald			degree C		
02a. RTC	KTS (VIC-	CR2032	3 Vdc, maximum	UL1642	UL,
		0112002	abnormal charge	OL 1042	JL,
Battery (BT2)	DAWN)		current 10 mA		
and DTO	NA't - L'-L'	ODOOO		111.4040	1.11
02b. RTC	Mitsubishi	CR2032	3 Vdc, maximum	UL1642	UL,
Battery (BT2)	Electric Corp.		abnormal charge		
(Alternate)			current 10 mA		
02c. RTC Battery	Matsushita	CR2032	3 Vdc, maximum	UL1642	UL,
(Alternate)	Electric Industrial		abnormal charge		
	Co Ltd		current 10 mA		
	(Panasonic)				
02d. RTC	Sony Fukushima	CR2032	3 Vdc, maximum	UL1642	UL,
Battery	Corp.		abnormal charge		
(Alternate)	·		current 10 mA		
02e. RTC	Toshiba Battery	CR2032	3 Vdc, maximum	UL1642	UL,
Battery	Co., Ltd.		abnormal charge		,
(Alternate)			current 10 mA		
03. CPU Fan	Delta Electronics	AFB0812HHD	12 Vdc, 0.24 A,	UL507,EN	UL, VDE
	Inc.	/ " 500 121 11 15	(max. 0.4 A)	60950	02, 102
			51.211CFM,	00000	
			max. 4.80 W		
04a-01.	Bourns Inc	MF-USMF110	1.1 A, 6 Vdc	UL 1434	UL,
Polyswitch (FS4)	Douirio ilio	IVII -OOIVII I IO	1.1 A, 0 Vuc	OL 1404	JL,
(for VGA port)					
	Tyco Electronics	MicroSMD110	1 1 1 6 \/da	EN 60720 4 LU	III TIIV
04a-02.		MicroSMD110	1.1A, 6 Vdc	EN 60730-1 UL	UL, TUV
Polyswitch	Corp. Raychem			1434	
(FS4)(for VGA	Circuit Protection				
port) (alternate)	Div	OMPAGASSASS	454041	EN 00700 4 1 "	1.11 T 1.15 /
04b-01.	Polytronics	SMD1812P150T	1.5 A, 24 Vdc	EN 60730-1 UL	UL, TUV
Polyswitch (FS2)	Technology	/24		1434	
(for 1394 port)					
04b-02.	Tyco Electronics	miniSMDC150/2	1.5 A, 24 Vdc	EN 60730-1 UL	UL, TUV
Polyswitch (FS2)	Corp. Raychem	4		1434	
(for 1394 port)	Circuit Protection				
(alternate)	Div				
,	•	•	•	•	

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	IEC 60950-1		
Clause	Requirement + Test	Result - Remark	Verdict

04c-01. Polyswitch (FS1, FS3) (FS1 for rear USB) (FS3 for front USB)	Tyco Electronics Corp. Raychem Circuit Protection Div	SMD1812P260T F	2.6 A, 6 Vdc	EN 60730-1 UL 1434	UL, TUV
04c-02. Polyswitch (FS1, FS3) (FS1 for rear USB) (FS3 for front USB) (alternate)	Tyco Electronics Corp. Raychem Circuit Protection Div	miniSMDC260F-2	2.6 A, 6 Vdc	EN 60730-1 UL1434	UL, TUV
05. CPU Heatsink			Aluminum part and copper part. Overall 85 by 85 by 40.5 mm		,
05a. CPU Heatsink (Alternate)			Aluminum part. Overall 85 by 85 by 40.5 mm		,
06. Heatsink (for south bridge)			Aluminum, overall 42.5 mm by 42.5 mm by 20.8 mm details.		,
07. Heatsink (for noruth bridge)			Aluminum, overall 37.5 mm by 37.5 mm by 6 mm		,
08. Heatsink (HS1, HS2, HS3)			Aluminum, overall 25 mm by 24.7 mm by 18 mm		,
09. Resistor (R66)			Rated 1 K ohm		,
For Main Board, MSI, type MS- 7259:					,
01. Heat sink for CPU used			Aluminum part. Overall 85 by 85 by 40.5 mm		,
01a. Heat sink for CPU used (Alternate)			Aluminum part and copper part. Overall 85 by 85 by 40.5 mm		,
02. R.T.C. Battery (JBAT2)	Vic-Dawn Enterprise Co., Ltd	CR2032	3 Vdc, 160 mAh, maximum abnormal charge current 10 mA. The reverse current	UL1642	UL,

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	IEC 60950-1		
Clause	Requirement + Test	Result - Remark	Verdict

			protection is accomplished by series circuit of a diode (D4) with a 1 K ohm resistor (R47)		
02a. R.T.C. Battery (JBAT2) (Alternate)	Mitsubishi Electric Corp.	CR2032	3.3 Vdc, 200 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a diode (D4) with a 1 K ohm resistor (R47)	UL1642	UL,
02b. R.T.C. Battery (JBAT2) (Alternate)	Matsushita Electric Industrial Co., Ltd.	CR2032	3.2 Vdc, 220 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a diode (D4) with a 1 K ohm resistor (R47).	UL1642	UL,
02c. R.T.C. Battery (JBAT2) (Alternate)	Sony Energy Devices Corp.	CR2032	3.3 Vdc, 240 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a diode (D4) with a 1 K ohm resistor (R47).	UL1642	UL,
02d. R.T.C. Battery (JBAT2) (Alternate)	Toshiba Battery Co., Ltd.	CR2032	3.3 Vdc, 220 mAh, maximum abnormal charge current 10 mA. The reverse current	UL1642	UL,

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		IEC 60950-1		
Clause	Requirement + Test		Result - Remark	Verdict

			protection is accomplished by series circuit of a diode (D4) with a 1 K ohm resistor (R47)		
03. Polyswitch (FS1 for PS/2 and rear USB), (FS3 for front USB)	Tyco Electronics Corp Raychem Circuit Protection Div	miniSMDC260	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
03a. Polyswitch (FS1 for PS/2 and rear USB), (FS3 for front USB) (Alternate)	Polytronics Technology Corp.	SMD1812P260T S	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
03b. Polyswitch (FS1 for PS/2 and rear USB), (FS3 for front USB) (Alternate)	Polytronics Technology Corp.	SMD1812P260T F	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
04. Polyswitch (FS2 for IEEE1394)	Polytronics Technology Corp.	SMD1812P150T F/24	SMD type. Rated 24 Vdc. Ih: 1.5 A. It: 3.0 A.	UL1434	UL,
4a. Polyswitch (FS2 for IEEE1394) (Alternate)	Tyco Electronics Corp Raychem Circuit Protection Div	miniSMDC150/2 4	SMD type. Rated 24 Vdc. Ih: 1.5 A. It: 3.0 A.	UL1434	UL,
05. CPU Fan	Delta Electronics Inc.	AFB0812HHD	12 Vdc, 0.24 A, (max. 0.4 A) 51.211 CFM, max. 4.80 W	UL507,EN 60950	UL, VDE
05a. CPU Fan (Alternate)	Delta Electronics Inc.	AFB0812HD	12 Vdc, 0.27 A, 43.941 CFM	UL507	UL,
Main board, MSI. Type MS-7331:					,
01. Heat sink for CPU used			Aluminum part. Overall 85 by 85 by 40.5 mm		,
01a. Heat sink for CPU used (Alternate)			Aluminum part and copper part. Overall 85 by 85 by 40.5 mm		,
02. R.T.C. Battery (VBAT1)	Vic-Dawn Enterprise Co., Ltd	CR2032	3 Vdc, 160 mAh, maximum abnormal charge current 10 mA. The reverse	UL1642	UL,

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	IEC 60950-1		
Clause	Requirement + Test	Result - Remark	Verdict

			current protection is accomplished by series circuit of a diode (D1) with a 1 K ohm resistor (R236)		
02a. R.T.C. Battery (VBAT1) (Alternate)	Mitsubishi Electric Corp.	CR2032	3.3 Vdc, 200 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a diode (D1) with a 1 K ohm resistor (R236)	UL1642	UL,
02b. R.T.C. Battery (VBAT1) (Alternate)	Sony Energy Devices Corp.	CR2032	3.3 Vdc, 240 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a diode (D1) with a 1 K ohm resistor (R236).	UL1642	UL,
02c. R.T.C. Battery (VBAT1) (Alternate)	Toshiba Battery Co., Ltd.	CR2032	3.3 Vdc, 220 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a diode (D1) with a 1 K ohm resistor (R236)	UL1642	UL,
03. Polyswitch (FS3 for PS/2 and rear USB), (FS4 for front USB)	Tyco Electronics Corp. Raychem Circuit Protection Div.	miniSMDC260	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,

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IEC 60950-1			
Clause	Requirement + Test	Result - Remark	Verdict

03a. Polyswitch (FS3 for PS/2 and rear USB), (FS4 for front USB) (Alternate)	Polytronics Technology Corp.	SMD1812P260T F	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.		UL,
03b. Polyswitch (FS3 for PS/2 and rear USB), (FS4 for front USB) (Alternate)	Polytronics Technology Corp.	SMD1812P260T S	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
03c. Polyswitch (FS3 for PS/2 and rear USB), (FS4 for front USB) (Alternate)	Littelfuse Inc.	1812L260MR	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
03d. Polyswitch (FS3 for PS/2 and rear USB), (FS4 for front USB) (Alternate)	Tyco Electronics Corp. Raychem Circuit Protection Div	miniSMDC260F- 2	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
04. CPU Fan	Delta Electronics Inc.		12 Vdc, 0.24 A (maximum 0.4 A), 51.211 CFM	UL507	UL,
04a. CPU Fan (Alternate)	Delta Electronics Inc.	AFB0812HD	12 Vdc, 0.27 A, 43.941 CFM	UL507	UL,
Main board, MSI. Type MS- 7334: [DVI connector is optionally provided.]					,
1. R.T.C. Battery (BAT1)	Matsushita Electric Industrial Co Ltd Panasonic Corp Of North America	CR2032	3.2 Vdc, 220 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a blocking diode (D8) with a 1 K ohm resistor (R258).	UL1642	UL,
1a. R.T.C. Battery (BAT1) (Alternate)	Vic-Dawn Enterprise Co., Ltd	CR2032	3 Vdc, 160 mAh, maximum abnormal charge current 10 mA.	UL1642	UL,

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IEC 60950-1			
Clause	Requirement + Test	Result - Remark	Verdict

1b. R.T.C. Battery (BAT1) (Alternate)	FDK Energy Co Ltd	CR2032	The reverse current protection is accomplished by series circuit of a blocking diode (D8) with a 1 K ohm resistor (R258). 3.3 Vdc, 220 mAh, maximum abnormal charge	UL1642	UL,
			current 10 mA. The reverse current protection is accomplished by series circuit of a blocking diode (D8) with a 1 K ohm resistor (R258).		
1c. R.T.C. Battery (BAT1) (Alternate)	Mitsubishi Electric Corp.	CR2032	3.3 Vdc, 200 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of a blocking diode (D8) with a 1 K ohm resistor (R258).	UL1642	UL,
2. Polyswitch for PS/2 and rear USB (FS1, FS2)	Polytronics Technology Corp.	SMD1812P150T (+)	SMD type. Rated 6 Vdc. Ih: 1.5 A. It: 3.0 A.	UL1434	UL,
2a. Polyswitch for PS/2 and rear USB (FS1, FS2) (Alternate)	Littelfuse Inc	1812X150PRT	SMD type. Rated 6 Vdc. Ih: 1.5 A. It: 3.0 A.		UL,
2b. Polyswitch for PS/2 and rear USB (FS1, FS2) (Alternate)	Bourns Inc	MF-MSMF150	SMD type. Rated 6 Vdc. Ih: 1.5 A. It: 3.0 A.		UL,
2c. Polyswitch for PS/2 and rear	Tyco Electronics Corp Raychem	miniSMDC150 (15)	SMD type. Rated 6 Vdc. Ih: 1.5 A.	UL1434	UL,

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Clause	Requirement + Test	Result - Remark	Verdict

USB (FS1, FS2)	Circuit Protection		It: 3.0 A.		
(Alternate)	Div				
3. Polyswitch for front USB (FS3)	Polytronics Technology Corp.	SMD1812P260T (+)	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
3a. Polyswitch for front USB (FS3) (Alternate)	Tyco Electronics Corp Raychem Circuit Protection Div	miniSMDC260 (26)	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.		UL,
3b. Polyswitch for front USB (FS3) (Alternate)	Littelfuse Inc	1812X260MR++	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.		UL,
4. Polyswitch for rear IEEE1394 (FS4)	Polytronics Technology Corp.	SMD1812P150T F/24	SMD type. Rated 24 Vdc. Ih: 1.5 A. It: 3.0 A.		UL,
4a. Polyswitch for rear IEEE1394 (FS4) (Alternate)	Tyco Electronics Corp Raychem Circuit Protection Div	miniSMDC150/2 4	SMD type. Rated 24 Vdc. Ih: 1.5 A. It: 3.0 A.		UL,
5. CPU Fan	Delta Electronics Inc.	AFB0812HHD	12 Vdc, 0.24 A (maximum 0.4 A), 51.211 CFM	UL507	UL,
5a. CPU Fan (Alternate)	Delta Electronics Inc.	AFB0812HD	12 Vdc, 0.27 A, 43.941 CFM	UL507	UL,
6. Heat sink for CPU used			Aluminum part. Overall 85 by 85 by 40.5 mm, the fin approx. 0.4 mm thickness minimum.		,
6a. Heat sink for CPU used (Alternate)			Aluminum part and copper part. Overall 85 by 85 by 40.5 mm, the fin approx. 0.4 mm thickness minimum.		,
Main board type MS-7407: (For Models MS- 6470XX and Hetis G31XX only)					,
01. RTC Battery (BAT1)	Matsushita Electric Industrial Co Ltd Panasonic Corp Of North	CR2032	3.2 Vdc, 220 mAh, maximum abnormal charge current 10mA. The reverse	UL1642	UL,

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Clause	Requirement + Test	Result - Remark	Verdict

	America		current protection is accomplished by series circuit of diode (D9, D10) with a 1 K ohm resistor (R143)		
01a. RTC Battery (BAT1) (Alternate)	VIC-Dawn Enterprise Co Ltd	CR2032	3 Vdc, 160 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of diode (D9, D10) with a 1 K ohm resistor (R143)	UL1642	UL,
01b. RTC Battery (BAT1) (Alternate)	FDK Energy Co Ltd	CR2032	3.3 Vdc, 220 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of diode (D9, D10) with a 1 K ohm resistor (R143)	UL1642	UL,
01c. RTC Battery (BAT1) (Alternate)	Electric Corp	CR2032	3.3 Vdc, 200 mAh, maximum abnormal charge current 10 mA. The reverse current protection is accomplished by series circuit of diode (D9, D10) with a 1 K ohm resistor (R143)	UL1642	UL,
02. Polyswitch for PS/2 (F3)	Polytronics Technology Corp.	SMD1210P110T F	SMD type. Rated 6 Vdc. Ih: 1.1 A. It: 2.2 A.		UL,
02a. Polyswitch for PS/2 (F3)	Tyco Electronics Corp Raychem	microSMD110	SMD type. Rated 6 Vdc. Ih: 1.1 A.	UL1434	UL,

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Clause	Requirement + Test	Result - Remark	Verdict

(Alternate)	Circuit Protection		It: 2.2 A.		
02b. Polyswitch for PS/2 (F3) (Alternate)	Bourns Inc	MF-MSMF110	SMD type. Rated 6 Vdc. Ih: 1.1 A. It: 2.2 A.	UL1434	UL,
03. Polyswitch for USB (F1, F5)	Polytronics Technology Corp.	SMD1812P260T F	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
03a. Polyswitch for USB (F1, F5) (Alternate)	Tyco Electronics Corp Raychem Circuit Protection Div	miniSMDC260	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
03b. Polyswitch for USB (F1, F5) (Alternate)	Littelfuse Inc	1812X260	SMD type. Rated 6 Vdc. Ih: 2.6 A. It: 5.2 A.	UL1434	UL,
04. Polyswitch for rear 1394 (F2)	Polytronics Technology Corp.	SMD1812P150T F/24	SMD type. Rated 24 Vdc. Ih: 1.5 A. It: 3.0 A.		UL,
04a. Polyswitch for rear 1394 (F2) (Alternate)	Tyco Electronics Corp Raychem Circuit Protection Div	miniSMDM150/2 4	SMD type. Rated 24 Vdc. Ih: 1.5 A. It: 3.0 A.	UL1434	UL,
05. CPU Fan	Delta Electronics Inc.	AFB0812HHD	12Vdc, 0.24A (maximum 0.4A), 51.211CFM	UL507	UL,
05a. CPU Fan (Alternate)	Delta Electronics Inc.	AFB0812HD	12Vdc, 0.2A (maximum 0.27A), 43.941CFM,	UL507	UL,
06. Heat sink for CPU used			Aluminum part. Overall 85 by 85 by 40 mm. See Enclosure Diagrams 04-07 for details.		,
06a. Heat sink for CPU used (with insert copper) (Alternate)			Aluminum part and copper part. Overall 85 by 85 by 40.5 mm. See Enclosure Diagrams 04-06 for details.		,
Maniboard (for models MS- 6618XXXX and Hetis G41XXXX)	Micro-Star International Co., Ltd.	MS-7430	See photo 3-26, 3-27, 3-28, 3-29		,
01. RTC Battery	Matsushita Electric Industrial	CR2032	Rated 3 V, maximum	UL 1642	UL,

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Clause	Requirement + Test	Result - Remark	Verdict

01a. RTC Battery (alternate)	Co. Ltd. Panasonic Corp Of North America Vic-Dawn Enterprise Co., Ltd.	CR2032	abnormal charging current 10mA. The reverse current protection is accomplished by series circuit of diode (D10) with a 1 K ohm resistor (R143) Rated 3 V, maximum abnormal charging current	UL 1642	UL,
			10mÅ. The reverse current protection is accomplished by series circuit of diode (D10) with a 1 K ohm resistor (R143)		
O2a-1.Poly Switch (F2) (for rear side IEEE 1394 port)	Polytronics Technology Corp	SMD1812P150T F/24	24V, 1.5 A, CA = 3	UL 1434	UL,
O2a-2.Poly Switch (F2) (for rear side IEEE 1394 port) (alternate)	Tyco Electronics Corp Raychem Circuit Protection Div.	miniSMDC150F/ 24-2	24V, 1.5 A, CA = 3	UL 1434	UL,
03.Overcurrent Protector for USB and PS/2 (CONN2A, CONN3B, CONN5, CONN6)	UPI Semiconductor Corp	uP7533	Voltage Range: 4.5-5.5Vdc, Maximum Continuous Current: 1.5A, Protective Current: 3.5A	UL Subject 2367	UL,
04. Heat sink for CPU used			Aluminum part. Overall 85 by 85 by 40 mm. See Enclosure Diagrams 04-07 for details.		,
04a. Heat sink for CPU used			Aluminum part and copper part.		,

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Clause	Requirement + Test		Result - Remark	Verdict

(with insert			Overall 85 by 85		
copper)			by 40.5 mm.		
(Alternate)			See Enclosure		
			Diagrams 04-06		
			for details.		
05. Heatsink			Aluminum. See		,
(HS1)			Enclosure		
,			Diagrams 04-11		
			for details.		
06. Heatsink (for			Aluminum. See		,
Q15,Q 16,Q			Enclosure		
11,Q			Diagrams 04-12		
12,Q17,Q18,Q19			for details.		
,Q20,Q21,Q23,Q					
31,Q32)					
07. CPU Fan	Delta Electronics	AFB0812HHD	12Vdc, 0.24A	UL507	UL,
	Inc.		(maximum 0.4A),		,
			51.211CFM		
07a. CPU Fan	Delta Electronics	AFB0812HD	12Vdc, 0.2A	UL507	UL,
(Alternate)	Inc.		(maximum		
,			0.27A),		
			43.941CFM		

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Enclosure

Photographs

Supplement Id	Description
3-01	Overall View (1/2)
3-02	Overall View (2/2)
3-03	Interior View
3-04	Main Board Component Side View
3-05	Main Board Layout Side
3-06	CPU Heatsink Top View
3-07	CPU Heatsink Bottom View
3-08	Front View without Plastic Panel
3-09	Top view of motherboard(MSI/MS-7231)
3-11	Front view of motherboard(MSI/MS-7231)
3-12	Top view of motherboard(MSI/MS-7259)
3-13	Bottom view of motherboard(MSI/MS-7259)
3-14	Top View of Mainboard type MS-7331
3-15	Bottom View of Mainboard type MS-7331
3-16	Top View of Mainboard type MS-7334. (for Models MS-6441XX, Hetis 965XX)
3-17	Bottom View of Mainboard type MS-7334. (for Models MS-6441XX, Hetis 965XX)
3-18	Front View of Models MS-6441XX, Hetis 965XX
3-19	Back View of Models MS-6441XX, Hetis 965XX
3-20	Top view of Mainboard type MS-7407
3-21	Bottom view of Mainboard type MS-7407
3-22	Unit overview with alternate enclosure - 01
3-23	Unit overview with alternate enclosure - 02
3-24	Unit overview with alternate enclosure - 03
3-25	Plasitc Stand Base
3-26	Top view of Mainboard type MS-7430
3-27	Bottom view of Mainboard type MS-7430
3-28	Connectors view of Mainboard (type MS-7430) -01
3-29	Connectors view of Mainboard (type MS-7430) -02

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Enclosure

Diagrams

Supplement Id	Description
4-01	Enclosure Drawing
4-02	HS1-HS3 Heatsink Drwaing
4-03	915 Chipset Heatsink Drwaing
4-04	ICH6 Chipset Heatsink Drwaing
4-06	CPU Heatsink Drwaing (Insert Copper) of Models MS-6470XX, Hetis G31XX, MS-6618XXXX and Hetis G41XXXX
4-07	CPU Heatsink Drwaing (without Insert Copper) of Models MS-6470XX, Hetis G31XX, MS-6618XXXX and Hetis G41XXXX
4-09	Encloaure Drawing (alternate)
4-10	Plastic Stand Base
4-11	Heatsink Drawing (HS1) (Mainboard, MSI, type MS-7430)
4-12	Heatsink Drawing (for Q15,Q 16,Q 11,Q 12,Q17,Q18,Q19,Q20,Q21,Q23,Q31,Q32) (Mainboard, MSI, type MS-7430)
4-13	Metal mesh for systemm fan